

Abstract**METHOD OF TEACHING EYEPOINTS FOR WIRE BONDING AND RELATED
SEMICONDUCTOR PROCESSING OPERATIONS**

A method of teaching an eyepoint for a wire bonding operation is provided. The method includes (1) selecting a group (306, 308) of shapes from a region of a semiconductor device for use as an eyepoint (310), and (2) teaching the eyepoint to a wire bonding machine using at least one of (a) a sample semiconductor device, or (b) predetermined data related to the semiconductor device. The teaching step includes defining locations of each of the shapes with respect to one another.

Fig. 3